SELF-OSCILLATING HALF-BRIDGE

Features

- Output Power MOSFETs in half-bridge configuration 500V Rated Breakdown Voltage
- High side gate drive designed for bootstrap operation
- Bootstrap diode integrated into package
- Accurate timing control for both Power MOSFETs Matched delay to get 50% duty cycle Matched deadtime of 1.2us
- Internal oscillator with programmable frequency

$$f = \frac{1}{1.4 \times (RT + 75\Omega) \times CT}$$

- Zener clamped Vcc for offline operation
- Half-bridge output is out of phase with R_T

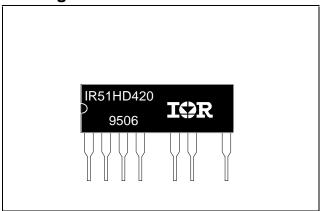
Description

The IR51HD420 is a high voltage, high speed, selfoscillating half-bridge. Proprietary HVIC and latch immune CMOS technologies, along with the HEXFET® power MOSFET technology, enable ruggedized single package construction. The front-end features a programmable oscillator which functions similar to the CMOS 555 timer. The supply to the control circuit has a zener clamp to simplify offline operation. The output features two HEXFETs in a half-bridge configuration with an internally set deadtime designed for minimum cross-conduction in the half-bridge. Propagation delays for the high and low side power MOSFETs are matched to simplify use in 50% duty cycle applications. The device can operate up to 500 volts.

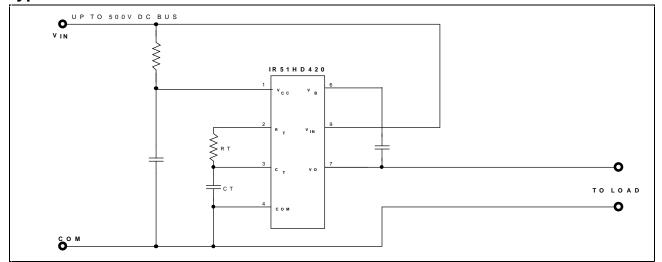
Product Summary

V _{IN} (max)	500V
Duty Cycle	50%
Deadtime	1.2µs
R _{DS(on)}	3.0Ω
$P_D (T_A = 25 ^{\circ}C)$	2.0W

Package



Typical Connection





Absolute Maximum Ratings

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM, all currents are defined positive into any lead. The Thermal Resistance and Power Dissipation ratings are measured under board mounted and still air conditions.

	Parameter			
Symbol	Definition	Min.	Max.	Units
V _{IN}	High Voltage Supply	-0.3	500	
V_{B}	High Side Floating Supply Absolute Voltage	-0.3	525	
VO	Half-Bridge Output Voltage	-0.3	V _{IN} + 0.3	V
V_{RT}	R _T Voltage	-0.3	$V_{CC} + 0.3$]
V _{CT}	C _T Voltage	-0.3	V _{CC} + 0.3	
Icc	Supply Current (Note 1)		25	mΑ
I _{RT}	R _T Output Current	-5	5	
dv/dt	Peak Diode Recovery dv/dt		3.5	V/ns
P_D	Package Power Dissipation @ T _A ≤ +25°C		2.00	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		60	°C/W
TJ	Junction Temperature	-55	150	
Ts	Storage Temperature	-55	150	٥C
T_L	Lead Temperature (Soldering, 10 seconds)		300	

Recommended Operating Conditions

The Input/Output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions.

	Parameter			
Symbol	Definition	Min.	Max.	Units
V _B	High Side Floating Supply Absolute Voltage	VO + 10	VO + V _{CLAMP}	
V_{IN}	High Voltage Supply		500	V
VO	Half-Bridge Output Voltage	-5	500	
I _D	Continuous Drain Current (T _A = 25°C)		0.7	Α
	$(T_A = 85^{\circ}C)$		0.5	
Icc	Supply Current (Note 1)		5	mA
T _A	Ambient Temperature	-40	125	°C

Note 1: Because of the IR51HD420's application specificity toward off-line supply systems, this IC contains a zener clamp structure between the chip V_{CC} and COM which has a nominal breakdown voltage of 15.6V. Therefore, the IC supply voltage is normally derived by current feeding the V_{CC} lead (typically by means of a high value resistor connected between the chip V_{CC} and the rectified line voltage and a local decoupling capacitor from V_{CC} to COM) and allowing the internal zener clamp circuit to determine the nominal supply voltage. Therefore, this circuit should not be driven by a DC, low impedance power source of greater than V_{CLAMP}.



Dynamic Electrical Characteristics

 V_{BIAS} (V_{CC} , V_{B}) = 12V unless otherwise specified.

	Parameter	$T_A = 25^{\circ}C$				
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
t _{rr}	Reverse Recovery Time (MOSFET Body Diode)		240		ns	I _F = 700mA
Q _{rr}	Reverse Recovery Charge (MOSFET Body Diode)		0.7		μC	di/dt = 100A/µs
DT	Deadtime, LS Turn-Off to HS Turn-On & HS Turn-Off to LS Turn-On		1.2		μs	
D	R _T Duty Cycle		50		%	$f_{OSC} = 20 \text{ kHz}$

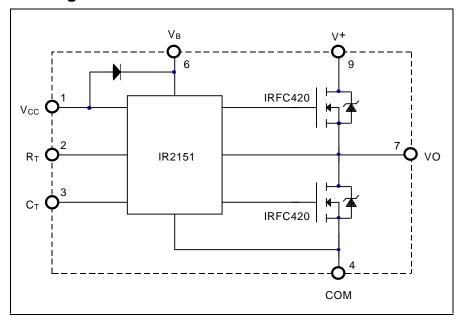
Static Electrical Characteristics

 V_{BIAS} (V_{CC} , V_{B}) = 12V unless otherwise specified.

	Parameter T _A = 25°C					
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
Supply	Characteristics					
V _{CCUV+}	V _{CC} Supply Undervoltage Positive Going Threshold		8.4		٧	
V _{CCUV} -	V _{CC} Supply Undervoltage Negative Going Threshold		8.0			
Iqcc	Quiescent V _{CC} Supply Current		300		μA	
V_{CLAMP}	V _{CC} Zener Shunt Clamp Voltage		15.6		V	$I_{CC} = 5 \text{ mA}$
Floating	Supply Characteristics	_				
I _{QBS}	Quiescent V _{BS} Supply Current		30		μA	
los	Offset Supply Leakage Current 50		V			$_{B} = V_{IN} = 500V$
Oscillate	or I/O Characteristics					
fosc	Oscillator Frequency		20		kHz	$R_T = 35.7 \text{ k}\Omega,$ $C_T = 1 \text{ nF}$
			100			$R_T = 7.04 \text{ k}\Omega,$ $C_T = 1 \text{ nF}$
I _{CT}	C _T Input Current		0.001	1.0	μA	
V _{CTUV}	C _T Undervoltage Lockout 100			2.5	V < V	cc < Vccuv+
V_{RT} +	R_T High Level Output Voltage, V_{CC} - R_T		20			$I_{RT} = -100 \mu A$
			200		mV	$I_{RT} = -1 \text{ mA}$
$V_{RT^{-}}$	R _T Low Level Output Voltage		20			$I_{RT} = 100 \mu A$
			200			$I_{RT} = 1 \text{ mA}$
V_{RTUV}	R _T Undervoltage Lockout, V _{CC} - R _T		100			$2.5V < V_{CC} < V_{CCUV+}$
V _{CT} +	2/3 V _{CC} Threshold		8.0		V	
V _{CT} -	1/3 V _{CC} Threshold		4.0			
Output (Output Characteristics					
R _{DS(on)}	Static Drain-to-Source On-Resistance		3.0		Ω	$I_D = 500 \text{mA}$
V_{SD}	Diode Forward Voltage 0.8				V	T _i = 150 °C



Functional Block Diagram

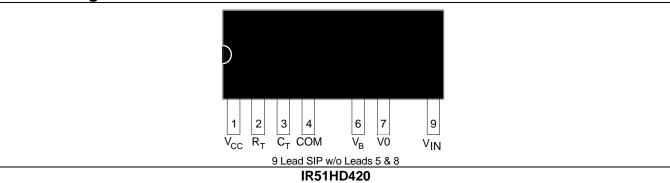


Lead Definitions

	Load Domitions			
	Lead			
Symbol	Description			
Vcc	Logic and internal gate drive supply voltage. An internal zener clamp diode at 15.6 V nominal is included to allow the Vcc to be current fed directly from V _{IN} typically by means of a high value resistor.			
R _T	Oscillator timing resistor input; a resistor is connected from R_T to C_T . R_T is out of phase with the half-bridge output (VO).			
Ст	Oscillator timing capacitor output; a capacitor is connected from C _T to COM in order to program the oscillator frequency according to the following equation:			
l	$f = \frac{1}{1.4 \times (RT + 75\Omega) \times CT}$			
	where 75 Ω is the effective impedance of the R _T output stage.			
V_B	High side gate drive floating supply. For bootstrap operation a high voltage fast recovery diode is needed to feed from V_{CC} to V_B .			
V_{IN}	High voltage supply.			
VO	Half-bridge output.			
COM	Logic and low side of half-bridge return.			



Lead Assignments



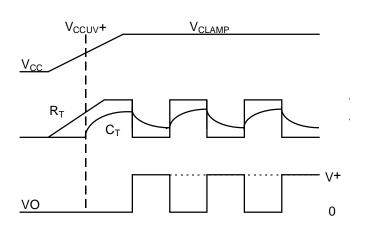


Figure 1. Input/Output Timing Diagram

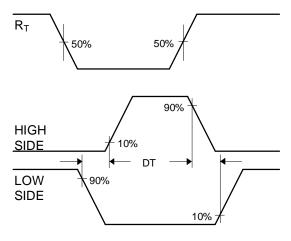
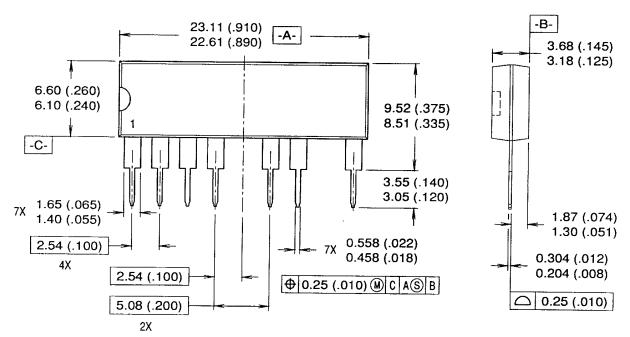


Figure 2. Deadtime Waveform Definitions





NOTES:

- 1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

Package Outline



WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331
EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020
IR CANADA: 7321 Victoria Park Ave., Suite 201, Markham, Ontario L3R 2Z8, Tel: (905) 475 1897
IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590
IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111
IR FAR EAST: 171 (K&H Bldg.), 30-4 Nishi-ikebukuro 3-Chome, Toshima-ku, Tokyo Japan Tel: 81 3 3983 0086
IR SOUTHEAST ASIA: 315 Outram Road, #10-02 Tan Boon Liat Building, Singapore 0316 Tel: 65 221 8371
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